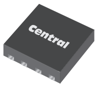
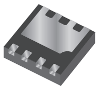
Package Details

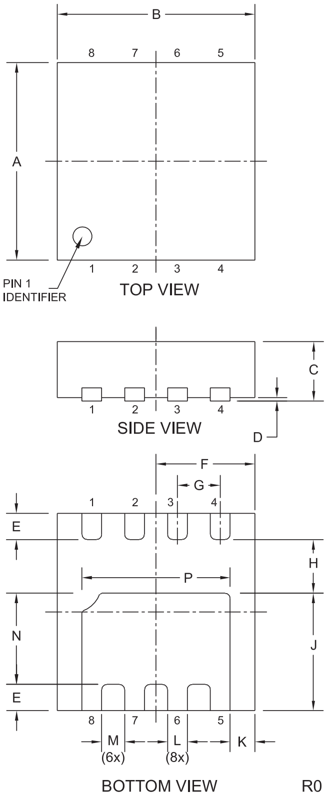
TLM833S Case


Top View


Bottom View

Central Semiconductor Corp.

Mechanical Drawing



DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.112	0.124	2.85	3.15
B	0.112	0.124	2.85	3.15
C	0.031	0.039	0.80	1.00
D	0.000	0.002	0.00	0.05
E	0.012	0.020	0.30	0.50
F	0.056	0.062	1.43	1.57
G	0.026		0.65	
H	0.030	0.033	0.75	0.85
J	0.065	0.073	1.65	1.85
K	0.012	0.016	0.30	0.40
L	0.010	0.014	0.25	0.35
M	0.012	0.016	0.30	0.40
N	0.047	0.057	1.20	1.45
P	0.081	0.091	2.07	2.32

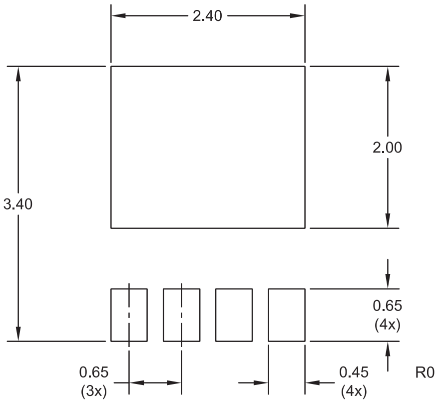
TLM833S (REV:R0)

Part Marking:
3-4 Character Alpha/Numeric Code

Lead Code:
Reference individual device datasheet.

Mounting Pad Geometry

(Dimensions in mm)



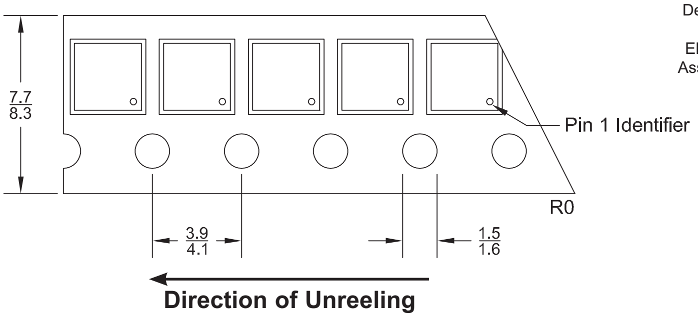
R0 (7-February 2012)

Package Details

TLM833S Case

Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 8mm



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-D

Packaging Base

7” Reel = 3,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7”	9	27,000	9x9x5	23x23x13	4	2
	18	54,000	9x9x9	23x23x23	8	4
	40	120,000	21x9x9	53x23x23	17	8
	108	324,000	27x9x17	69x23x43	45	21

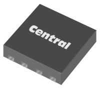
Ordering Information

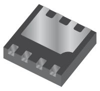
- For devices taped and reeled on 7” reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R0 (7-February 2012)

Material Composition Specification

TLM833S Case


Top View


Bottom View

Device average mass . . . . **24 mg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material (%wt)	Material (mg)	Substance	CAS No.	Substance (%wt)	Substance (mg)	Substance (ppm)
active device	doped Si	2.5%	0.6	Si	7440-21-3	2.5%	0.6	25,000
bond wire	gold	1.0%	0.24	Au	7440-57-5	1.0%	0.24	10,000
leadframe	Cu alloy w/ silver plating	30.9%	7.42	Cu	7440-50-8	30.1%	7.22	300,836
				Fe	7439-89-6	0.7%	0.173	7,208
				Zn	7440-66-6	0.04%	0.009	358
				Ag	7440-22-4	0.1%	0.015	637
die attach	silver epoxy	1.0%	0.24	epoxy resin	Proprietary	0.2%	0.05	2,083
				Ag	7440-22-4	0.8%	0.19	7,917
encapsulation*	EMC GREEN	55.0%	13.2	silica (fused)	60676-86-0	46.8%	11.22	467,504
				epoxy resin	Proprietary	3.5%	0.84	35,000
				epoxy, cresol novolac	29690-82-2	1.1%	0.263	10,954
				phenol resin	9003-35-4	3.5%	0.84	35,000
				carbon black	1333-86-4	0.2%	0.04	1,667
plating	matte tin	9.6%	2.3	Sn	7440-31-5	9.6%	2.3	95,834

*EMC GREEN molding compound is Halogen-Free.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R1 (3-June 2011)